



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Gregory E. Howard

Art Unit: 2824

Serial No.: 10/739,418

Examiner: TBD

Filed: 12/18/03

Docket: TI-35903

For: Flexible Package with Rigid Substrate Segments for High Density Integrated Circuit Systems

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on 4-13-04 as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz
Karen Vertz

4-13-04
Date

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are **EIGHT (8)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated
P.O. Box 655474 M/S 3999
Dallas, Texas 75265

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Reg. No. 20,250